

NUMBER: IQ14	REV: M	TITLE: Circuit Card Assembly (CCA) Requirements	
DOCUMENT OWNER: QUALITY MANAGER			
PREPARED BY: Will Distler	SIGNATURE: Will Distler	DATE: 04/11/2019	DEPT: Quality
APPROVED BY: Andrew Lawrence	SIGNATURE: Andrew Lawrence	DATE: 04/11/2019	DEPT: Quality

Outside vendors and the circuit card assemblies they supply shall conform to the following requirements from the latest revision of the indicated standard:

1. Assembly and soldering shall be in accordance with ANSI / IPC J-STD-001, Class 3, Post Soldering Cleanliness Designator C22.
2. Solder wire shall conform to SN63 alloy per Table A-2 of J-STD-006 (i.e., Kester 331)
3. Flux shall conform to low or medium activity level Organic per Table 1-1 of J-STD-004 (i.e., Kester 2331ZX)
4. Solder paste shall conform to J-STD-005 and J-STD-006 for alloy Sn63 (i.e., Kester HM531)

When alloys of solder other than Sn63 are considered for use, the supplier shall contact Palomar Products requesting approval.

When chemistry of flux other than Organic, low or medium activity is considered for use, the supplier shall contact Palomar Products requesting approval.

Workmanship shall be in accordance with ANSI / IPC A-610, Class 3. Target condition is preferred.

Exceptions/Clarifications to IPC A-610:

- a. Bonding shall be in accordance with DP70402-613 and the unique requirements of each drawing.
- b. Resistors dissipating 1 watt or greater shall be installed raised off the PWB .059" (no heat sink) or flush (heat sink).

The supplier shall certify with each shipment that the requirements of the Engineering drawing, purchase order and this attachment have been met.

Typed signatures constitute approval. Actual signatures on file at Palomar Products, Inc., Rancho Santa Margarita, CA